



Material Content Data Sheet



Sales Product Name	TLE7368-2E			Issued	19. July 2018			
MA#	MA001114798							
Package	PG-DSO-36-51			Weight*	733.31 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.773	2.01	2.01	20146	20146
leadframe	inorganic material	phosphorus	7723-14-0	0.092	0.01		125	
	non noble metal	zinc	7440-66-6	0.366	0.05		499	
	non noble metal	iron	7439-89-6	7.322	1.00		9985	
wire	non noble metal	copper	7440-50-8	297.304	40.54	41.60	405429	416038
	non noble metal	copper	7440-50-8	1.814	0.25	0.25	2474	2474
	encapsulation	organic material	carbon black	1333-86-4	0.798	0.11		1088
encapsulation	plastics	epoxy resin	-	36.690	5.00		50034	
	inorganic material	silicondioxide	60676-86-0	361.319	49.28	54.39	492726	543848
leadfinish	non noble metal	tin	7440-31-5	8.119	1.11	1.11	11072	11072
plating	noble metal	silver	7440-22-4	0.802	0.11	0.11	1093	1093
glue	plastics	epoxy resin	-	0.977	0.13		1332	
	noble metal	silver	7440-22-4	2.931	0.40	0.53	3997	5329
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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